TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSIII.5)

# 2SK1544

#### DC-DC Converter and Motor Drive Applications

- Low drain-source ON resistance  $: R_{DS} (ON) = 0.15 \Omega (typ.)$
- High forward transfer admittance  $|Y_{fs}| = 21 \text{ S (typ.)}$
- Low leakage current  $: I_{DSS} = 300 \ \mu A \ (max) \ (V_{DS} = 500 \ V)$
- Enhancement-mode :  $V_{th} = 1.5 \sim 3.5 \text{ V} (V_{DS} = 10 \text{ V}, \text{I}_{D} = 1 \text{ mA})$

#### Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V <sub>DSS</sub>	500	V	
Drain-gate voltage (R <sub>GS</sub> = 20 kΩ)		V <sub>DGR</sub>	500	V	
Gate-source voltage		V <sub>GSS</sub>	±30	V	
Drain current	DC (Note 1)	۱ <sub>D</sub>	25	A	
	Pulse (Note 1)	I <sub>DP</sub>	100		
Drain power dissipation (Tc = 25°C)		PD	200	W	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	-55~150	°C	

## **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch−c)</sub>	0.625	°C / W
Thermal resistance, channel to ambient	R <sub>th (ch−a)</sub>	35.7	°C / W

Weight: 9.75 g (typ.)

Note 1: Please use devices on condition that the channel temperature is below 150°C.

This transistor is an electrostatic sensitive device. Please handle with caution. Unit: mm

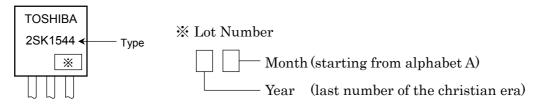
Electrical Characteristics (Ta = 25°C)

Chara	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	urrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±25 V, V <sub>DS</sub> = 0 V	—	_	±100	nA
Drain cut-off cu	rrent	I <sub>DSS</sub>	V <sub>DS</sub> = 500 V, V <sub>GS</sub> = 0 V	_	_	300	μA
Drain-source b	reakdown voltage	V (BR) DSS	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	500	_	—	V
Gate threshold	voltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	1.5	_	3.5	V
Drain-source O	N resistance	R <sub>DS (ON)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 13 A	_	0.15	0.20	Ω
Forward transfe	r admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 13 A	10	21	_	S
Input capacitan	ce	C <sub>iss</sub>		_	3700	_	
Reverse transfer capacitance		C <sub>rss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	400	_	pF
Output capacitance		C <sub>oss</sub>			920	_	
Switching time	Rise time	t <sub>r</sub>	$V_{GS} \stackrel{10V}{}_{0V} \int I_{D} = 13A$ $V_{GS} \stackrel{V_{OUT}}{}_{0V} \int I_{RL}$ $= 16\Omega$ $V_{U} = \pm 900V$	_	185	_	
	Turn-on time	t <sub>on</sub>		_	240	_	20
	Fall time	t <sub>f</sub>		_	250	_	ns
	Turn-off time	t <sub>off</sub>	$V_{DD} \rightleftharpoons 200V$ Duty $\leq 1\%$ , $t_w = 10 \mu s$	_	590	_	
Total gate charge (Gate-source plus gate-drain)		Qg		_	150	_	
Gate-source charge		Q <sub>gs</sub>	V <sub>DD</sub> ≈ 400 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 25 A		70		nC
Gate-drain ("miller") charge		Q <sub>gd</sub>			80		

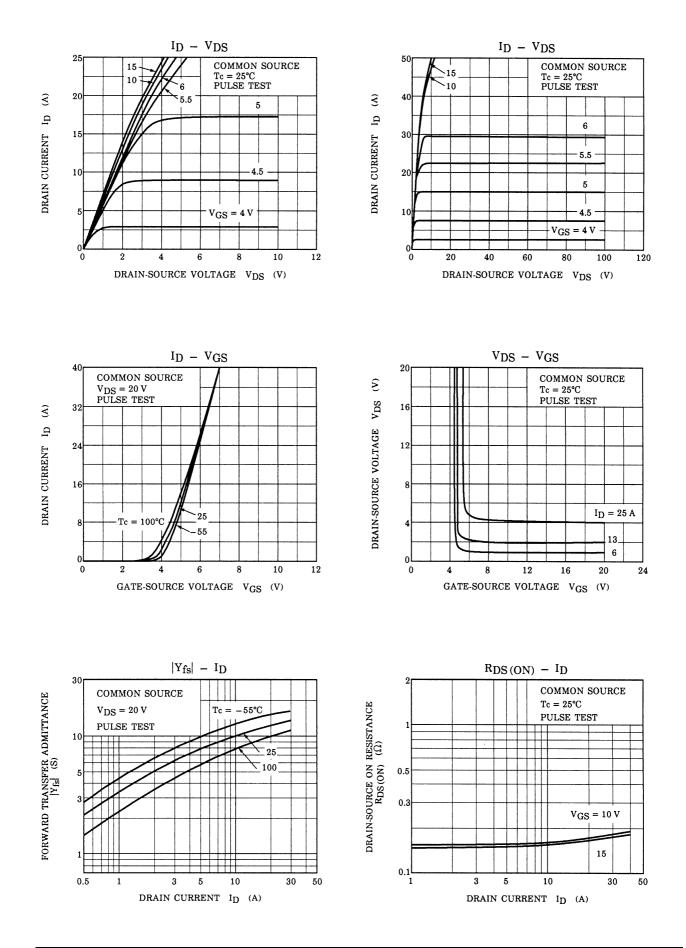
# Source–Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	_	_	_	25	А
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	_	_	_	100	А
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 25 A, V <sub>GS</sub> = 0 V	_	—	-1.6	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = 25 A, V <sub>GS</sub> = 0 V	_	780	_	ns
Reverse recovered charge	Qrr	dI <sub>DR</sub> / dt = 100 A / μs	_	9.8	_	μC

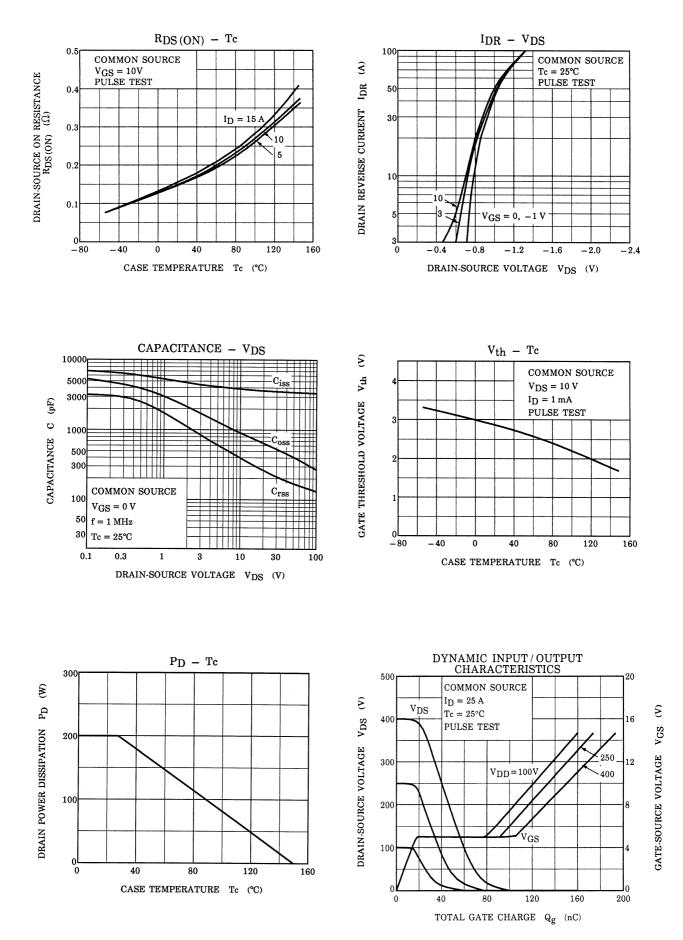
## Marking

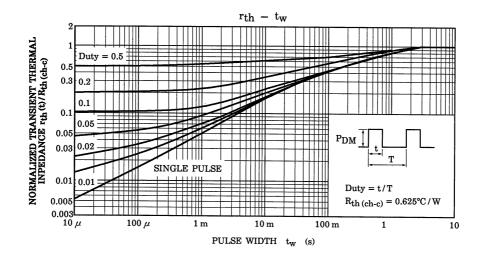


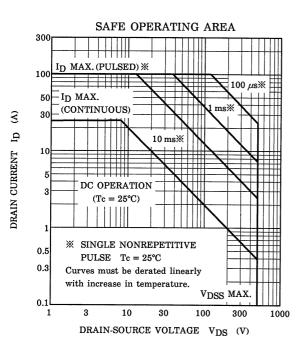
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